- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Outputs Are Precharged by Bias Voltage to Minimize Signal Distortion During Live Insertion

description

The SN74CBT6800A provides ten bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows bidirectional connections to be made while adding near-zero propagation delay. The device also precharges the B port to a user-selectable bias voltage (BIASV) to minimize live-insertion noise.

(TOP VIEW) 24 🛮 V_{CC} ON 23 B1 Α1 22 B2 Α2 аз Г 21 N B3 Α4 20 ∏ B4 Α5 19**∏** B5 18**∏** B6 Α6 17 B7 A7 Α8 16 B8 15 B9 Α9 10 14 B10 A10 13 BIASV **GND**

DB, DBQ, DGV, DW, OR PW PACKAGE

The SN74CBT6800A is organized as one 10-bit switch with a single enable (\overline{ON}) input. When \overline{ON} is low, the switch is on, and port A is connected to port B. When \overline{ON} is high, the switch between port A and port B is open. When \overline{ON} is high or V_{CC} is 0 V, B port is precharged to BIASV through the equivalent of a 10-k Ω resistor.

ORDERING INFORMATION

TA	PACKAGI	<u></u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC - DW	Tube	SN74CBT6800ADW	CBT6800A
	301C - DW	Tape and reel	SN74CBT6800ADWR	CB10000A
-40°C to 85°C	SSOP – DB	Tape and reel	SN74CBT6800ADBR	CT6800A
-40 C to 65 C	SSOP (QSOP) – DBQ	Tape and reel	SN74CBT6800ADBQR	CBT6800A
	TSSOP – PW	Tape and reel	SN74CBT6800APWR	CT6800A
	TVSOP – DGV	Tape and reel	SN74CBT6800ADGVR	CT6800A

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

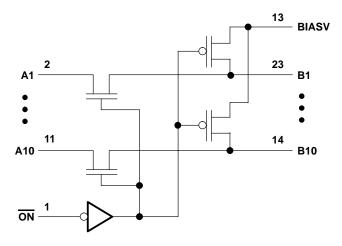
INPUT ON	FUNCTION
L	A port = B port
Н	A port = Z B port = BIASV



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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		
Bias voltage range, BIASV		0.5 V to 7 V
Input voltage range, V _I (see Note 1)		0.5 V to 7 V
Continuous channel current		128 mA
Input clamp current, I_{IK} ($V_I < 0$)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	: DB package	63°C/W
	DBQ package	61°C/W
	DGV package	86°C/W
	DW package	46°C/W
	PW package	88°C/W
Storage temperature range, T _{stg}	. •	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4	5.5	V
BIASV	Supply voltage	1.3	VCC	V
V _{IH}	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		8.0	V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAF	RAMETER		MIN	TYP [†]	MAX	UNIT		
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA				-1.2	V
II		$V_{CC} = 5.5 \text{ V},$	$V_I = 5.5 \text{ V or GND}$				±5	μΑ
lo		$V_{CC} = 4.5 \text{ V},$	BIASV = 2.4 V, $V_{O} = 0$		0.25			mA
Icc		V _{CC} = 5.5 V,	$I_{O} = 0,$	$V_I = V_{CC}$ or GND			50	μΑ
Δl _{CC} ‡	Control inputs	V _{CC} = 5.5 V,	One input at 3.4 V,	Other inputs at V _{CC} or GND			2.5	mA
Ci	Control inputs	V _I = 3 V or 0				3.5		pF
C _{o(OFF)}		$V_0 = 3 \text{ V or } 0,$	Switch off			4.5		pF
		$V_{CC} = 4 \text{ V},$ TYP at $V_{CC} = 4 \text{ V}$	V _I = 2.4 V,	I _I = 15 mA		11	20	
ron§			V _I = 0	I _I = 64 mA		3	7	Ω
		V _{CC} = 4.5 V	V = 0	I _I = 30 mA		3	7	
			V _I = 2.4 V,	I _I = 15 mA		6	15	

[†] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	TEST CONDITIONS	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V	V _{CC}	V _{CC} = 5 V ± 0.5 V	
	CONDITIONS	(IIVI O1)	(0011 01)	MIN MA	X MIN	MAX	
t_{pd} ¶		A or B	B or A	0.3	5	0.25	ns
^t PZH	BIASV = GND	ŌN	A or B		6 2	5.1	
t _{PZL}	BIASV = 3 V		AOIB		6 2	5.6	ns
t _{PHZ}	BIASV = GND	ŌN	A or B	5	5 1	5	
tPLZ	BIASV = 3 V	ON	Aorb	5	5 2	5.9	ns

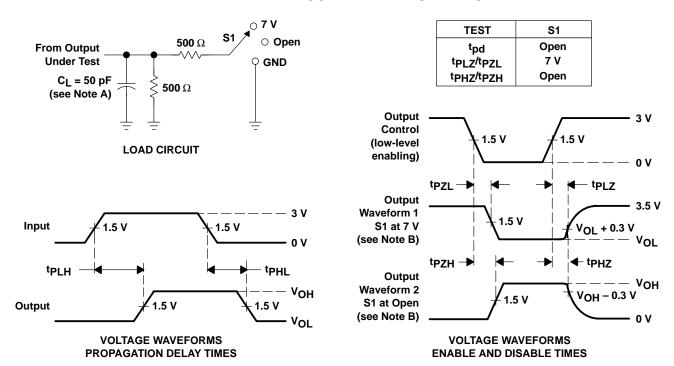
The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \,\Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74CBT6800APWR	Active	Production	TSSOP (PW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CT6800A
SN74CBT6800APWR.A	Active	Production	TSSOP (PW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CT6800A

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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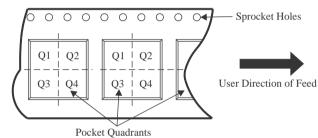
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ĺ	SN74CBT6800APWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Device Package Type		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74CBT6800APWR	TSSOP	PW	24	2000	353.0	353.0	32.0	



SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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